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**UPDATE CHANGE NOTIFICATION # 20802Z**

Generic Copy

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**Issue Date:** 24-Apr-2015

**TITLE:** Update to FPCN20802Z - Qualification of Sumitomo mold compound from G700HC to G700HF

**PROPOSED FIRST SHIP DATE:** 25-Feb-2016

**AFFECTED CHANGE CATEGORY(S):** Material Change

**ADDITIONAL RELIABILITY DATA:** Contact your local ON Semiconductor Sales Office or Chean Ching Sim <cheanching.sim@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office or Ahmad Faris Dzulkpli <AhmadFaris.Dzulkpli@onsemi.com>

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Mohd Hezri Abu Bakar <MohdHezri.AbuBakar@onsemi.com>

**NOTIFICATION TYPE:**

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

**DESCRIPTION AND PURPOSE:**

FPCN20802Z announces the change in mold compound on selected devices in DPAK package from Sumitomo G700HC to G700HF to improve delamination at post area.

This UN is issued to correct the Change part identification date code identified in the FPCN. Products assembled with mold compound G700HF from ON Semiconductor facility in Seremban, Malaysia will have a Finish Good Date Code no earlier than **WW08, 2016**.



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**List of affected General Parts:**

NTDV5804NT4G	NVD5867NLT4G
NVD4804NT4G	NVD5890NT4G
NVD4808NT4G	NVD6820NLT4G
NVD4810NT4G	NVD6824NLT4G
NVD5117PLT4G	NVD6828NLT4G
NVD5802NT4G	SVD5804NT4G
NVD5803NT4G	NVD5863NLT4G
NVD5806NT4G	NVD5865NLT4G
NVD5807NT4G	NVD5862NT4G